



# DDR4 3200 RDIMM

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VALIDATION RESULTS

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DDR4 RDIMM System-Level Validation Results on 3rd Gen Intel Xeon Scalable Processors listed below are the results from a small sample of DDR4 RDIMMS tested on Intel® Xeon® Scalable Processors on the Whitley and Cedar Island Platforms. We are providing this information as a guide to module compatibility with Intel Server reference platforms. This testing is not intended to replace the normal OEM qualification process. All parts used are recommended to be run with the latest Intel® platform Reference Code Production Version.

DDR4 RDIMM tested in the following conditions:  
 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

		DIMM			DRAM						Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev	
Kingston	KSM32RD8/32MER	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	2018	Rambus	B0	
Kingston	KSM32RD8/32MEM	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	2018	Montage	H1	
Kingston	KSM32RD8/32MEI	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	2018	IDT	C1	
Kingston	KSM32RS8/16MER	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	2020	Rambus	B0	
Kingston	KSM32RD4/64MER	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	2024	Rambus	B0	
Kingston	KSM32RD4/64MEM	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	2024	Montage	H1	
Kingston	KSM32RD4/64MEI	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	2024	IDT	C1	
Kingston	KSM32RS8/16MEM	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	2018	Montage	H1	
Kingston	KSM32RS8/16MEI	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	2018	IDT	C1	
Kingston	KSM32RS4/32MER	32GB	23	C3	Micron	MT40A4G4JC-062E:E	16Gb	x4	2024	Rambus	B0	
Kingston	KSM32RS4/32MEM	32GB	24	C3	Micron	MT40A4G4JC-062E:E	16Gb	x4	2024	Montage	H1	
Kingston	KSM32RS4/32MEI	32GB	25	C3	Micron	MT40A4G4JC-062E:E	16Gb	x4	2018	IDT	C1	
Kingston	KSM32RD8/32HAR	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	Rambus	B0	
Kingston	KSM32RD8/32HAM	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	Montage	H1	
Kingston	KSM32RD8/32HAI	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	IDT	C1	
Kingston	KSM32RS8/16HAR	16GB	22	D1	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	Rambus	B0	
Kingston	KSM32RS8/16HAM	16GB	22	D1	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	Montage	H1	
Kingston	KSM32RS8/16HAI	16GB	22	D1	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2026	IDT	C1	
Kingston	KSM32RD4/64HAR	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	Rambus	B0	
Kingston	KSM32RD4/64HAM	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	Montage	H1	
Kingston	KSM32RD4/64HAI	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	IDT	C1	
Kingston	KSM32RS4/32HAR	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	Rambus	B0	
Kingston	KSM32RS4/32HAM	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	Montage	H1	
Kingston	KSM32RS4/32HAI	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2010	IDT	C1	
Kingston	KSM32RD8/16HCR	16GB	22	E4	SK hynix	H5AN8G8NCJR-XNC	8Gb	x8	1950	Rambus	B0	
Kingston	KSM32RD8/16HCI	16GB	22	E4	SK hynix	H5AN8G8NCJR-XNC	8Gb	x8	1950	IDT	C1	
Kingston	KSM32RD4/32HDR	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	2009	Rambus	B0	
Kingston	KSM32RD4/32HDM	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	2009	Montage	H1	
Kingston	KSM32RD4/32HDI	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	2009	IDT	C1	
Kingston	KSM32RS8/16HCI	16GB	22	D1	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2101	IDT	C1	
Kingston	KSM32RS8/16HCR	16GB	22	D1	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2101	Rambus	B0	
Kingston	KSM32RD8/32HCI	32GB	22	E4	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2101	IDT	C1	
Kingston	KSM32RD8/32HCM	32GB	22	E4	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2101	Montage	H1	
Kingston	KSM32RD8/32HCR	32GB	22	E4	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2101	Rambus	B0	
Kingston	KSM32RS4/32HCI	32GB	22	C3	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2101	IDT	C1	
Kingston	KSM32RS4/32HCR	32GB	22	C3	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2101	Rambus	B0	
Kingston	KSM32RD4/64HCI	64GB	22	B4	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2101	IDT	C1	
Kingston	KSM32RD4/64HCM	64GB	22	B4	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2101	Montage	H1	

DDR4 RDIMM tested in the following conditions:  
 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

		DIMM			DRAM					Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev
Kingston	KSM32RD4/64HCR	64GB	22	B4	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2101	Rambus	B0
Micron Technology	MTA18ASF2G72PZ-3G2E2	16GB	22	C2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2028	Rambus	B0
Micron Technology	MTA18ASF2G72PZ-3G2E2	16GB	22	C2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2028	Montage	H1
Micron Technology	MTA18ASF2G72PZ-3G2E2	16GB	22	C2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2028	IDT	C1
Micron Technology	MTA9ASF1G72PZ-3G2E2	8GB	22	D1	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	Rambus	B0
Micron Technology	MTA9ASF1G72PZ-3G2E2	8GB	22	D1	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	Montage	H1
Micron Technology	MTA9ASF1G72PZ-3G2E2	8GB	22	D1	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	IDT	C1
Micron Technology	MTA36ASF4G72PZ-3G2E7	32GB	22	B2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2028	Rambus	B0
Micron Technology	MTA36ASF4G72PZ-3G2E7	32GB	22	B2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2028	Montage	H1
Micron Technology	MTA36ASF4G72PZ-3G2E7	32GB	22	B2	Micron	MT40A2G4SA-062E:E	8Gb	x4	2105	IDT	C1
Micron Technology	MTA18ASF2G72PDZ-3G2E1	16GB	22	E2	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	Rambus	B0
Micron Technology	MTA18ASF2G72PDZ-3G2E1	16GB	22	E2	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	Montage	H1
Micron Technology	MTA18ASF2G72PDZ-3G2E1	16GB	22	E2	Micron	MT40A1G8SA-062E:E	8Gb	x8	2028	IDT	C1
Micron Technology	MTA36ASF4G72PZ-3G2J3	32GB	22	B2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	Rambus	B0
Micron Technology	MTA36ASF4G72PZ-3G2J3	32GB	22	B2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	Montage	H1
Micron Technology	MTA36ASF4G72PZ-3G2J3	32GB	22	B2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	IDT	C1
Micron Technology	MTA18ASF2G72PZ-3G2J3	16GB	22	C2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	Rambus	B0
Micron Technology	MTA18ASF2G72PZ-3G2J3	16GB	22	C2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	Montage	H1
Micron Technology	MTA18ASF2G72PZ-3G2J3	16GB	22	C2	Micron	MT40A2G4SA-062E:J	8Gb	x4	1918	IDT	C1
Micron Technology	MTA18ASF2G72PDZ-3G2J3	16GB	22	E2	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	Rambus	B0
Micron Technology	MTA18ASF2G72PDZ-3G2J3	16GB	22	E2	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	Montage	H1
Micron Technology	MTA18ASF2G72PDZ-3G2J3	16GB	22	E2	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	IDT	C1
Micron Technology	MTA9ASF1G72PZ-3G2J3	8GB	22	D1	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	Rambus	B0
Micron Technology	MTA9ASF1G72PZ-3G2J3	8GB	22	D1	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	Montage	H1
Micron Technology	MTA9ASF1G72PZ-3G2J3	8GB	22	D1	Micron	MT40A1G8SA-062E:J	8Gb	x8	1918	IDT	C1
Micron Technology	MTA36ASF8G72PZ-3G2E1	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	1938	Rambus	B0
Micron Technology	MTA36ASF8G72PZ-3G2E1	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	1938	IDT	C1
Micron Technology	MTA18ASF4G72PZ-3G2E1	32GB	22	C2	Micron	MT40A4G4JC-062E:E	16Gb	x4	1940	Rambus	B0
Micron Technology	MTA18ASF4G72PZ-3G2E1	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	1940	Rambus	B0
Micron Technology	MTA9ASF2G72PZ-3G2E1	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	1940	Rambus	B0
Micron Technology	MTA36ASF8G72PZ-3G2E1	64GB	22	B4	Micron	MT40A4G4JC-062E:E	16Gb	x4	1938	Montage	H1
Micron Technology	MTA18ASF4G72PZ-3G2E1	32GB	22	C2	Micron	MT40A4G4JC-062E:E	16Gb	x4	1942	Montage	H1
Micron Technology	MTA18ASF4G72PZ-3G2E1	32GB	22	C2	Micron	MT40A4G4JC-062E:E	16Gb	x4	1940	IDT	C1
Micron Technology	MTA18ASF4G72PDZ-3G2E1	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	1938	Montage	H1
Micron Technology	MTA18ASF4G72PDZ-3G2E1	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	1938	IDT	C1
Micron Technology	MTA18ASF4G72PDZ-3G2E1	32GB	22	E4	Micron	MT40A2G8JC-062E:E	16Gb	x8	1940	Rambus	B0
Micron Technology	MTA9ASF2G72PZ-3G2E1	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	1940	Montage	H1
Micron Technology	MTA9ASF2G72PZ-3G2E1	16GB	22	D1	Micron	MT40A2G8JC-062E:E	16Gb	x8	1940	IDT	C1

DDR4 RDIMM tested in the following conditions:  
 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

		DIMM			DRAM					Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev
Micron Technology	MTA36ASF8G72PZ-3G2B2	64GB	22	B3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	Rambus	B0
Micron Technology	MTA36ASF8G72PZ-3G2B2	64GB	22	B3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	IDT	C1
Micron Technology	MTA36ASF8G72PZ-3G2B2	64GB	22	B3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	Montage	H1
Micron Technology	MTA18ASF4G72PZ-3G2B1	32GB	22	C3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	Rambus	B0
Micron Technology	MTA18ASF4G72PZ-3G2B1	32GB	22	C3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	Montage	H1
Micron Technology	MTA18ASF4G72PZ-3G2B1	32GB	22	C3	Micron	MT40A4G4VA-062E:B	16Gb	x4	1918	IDT	C1
Micron Technology	MTA18ASF4G72PDZ-3G2B1	32GB	22	E3	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	Rambus	B0
Micron Technology	MTA18ASF4G72PDZ-3G2B1	32GB	22	E3	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	Montage	H1
Micron Technology	MTA18ASF4G72PDZ-3G2B1	32GB	22	E3	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	IDT	C1
Micron Technology	MTA9ASF2G72PZ-3G2B1	16GB	22	D1	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	Rambus	B0
Micron Technology	MTA9ASF2G72PZ-3G2B1	16GB	22	D1	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	Montage	H1
Micron Technology	MTA9ASF2G72PZ-3G2B1	16GB	22	D1	Micron	MT40A2G8VA-062E:B	16Gb	x8	1918	IDT	C1
Micron Technology	MTA18ASF4G72PDZ-3G2B2	32GB	22	E4	Micron	MT40A2G8VA-062E:B	16Gb	x8	1944	Rambus	B0
Micron Technology	MTA18ASF4G72PDZ-3G2B2	32GB	22	E4	Micron	MT40A2G8VA-062E:B	16Gb	x8	1936	Montage	H1
Micron Technology	MTA18ASF4G72PDZ-3G2B2	32GB	22	E4	Micron	MT40A2G8VA-062E:B	16Gb	x8	1938	IDT	C1
Micron Technology	MTA18ASF2G72PDZ-3G2R1	16GB	22	E2	Micron	MT40A1G8SA-062E:R	8Gb	x8	2108	Rambus	B0
Micron Technology	MTA18ASF2G72PDZ-3G2R1	16GB	22	E2	Micron	MT40A1G8SA-062E:R	8Gb	x8	2106	Montage	H1
Micron Technology	MTA18ASF2G72PDZ-3G2R1	16GB	22	E2	Micron	MT40A1G8SA-062E:R	8Gb	x8	2108	IDT	C1
Micron Technology	MTA36ASF4G72PZ-3G2R1	32GB	22	B2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	Rambus	B0
Micron Technology	MTA36ASF4G72PZ-3G2R1	32GB	22	B2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	Montage	H1
Micron Technology	MTA36ASF4G72PZ-3G2R1	32GB	22	B2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	IDT	C1
Micron Technology	MTA18ASF2G72PZ-3G2R1	16GB	22	C2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	Rambus	B0
Micron Technology	MTA18ASF2G72PZ-3G2R1	16GB	22	C2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	Montage	H1
Micron Technology	MTA18ASF2G72PZ-3G2R1	16GB	22	C2	Micron	MT40A2G4SA-062E:R	8Gb	x4	2106	IDT	C1
Micron Technology	MTA9ASF1G72PZ-3G2R1	8GB	22	D1	Micron	MT40A1G8SA-062E:R	8Gb	x8	2106	Rambus	B0
Micron Technology	MTA9ASF1G72PZ-3G2R1	8GB	22	D1	Micron	MT40A1G8SA-062E:R	8Gb	x8	2106	Montage	H1
Micron Technology	MTA9ASF1G72PZ-3G2R1	8GB	22	D1	Micron	MT40A1G8SA-062E:R	8Gb	x8	2106	IDT	C1
Nanya Technology	NT16GA72D8PFX3P-JR	16GB	22	E2	Nanya	NT5AD1024M8F3-JR	8Gb	x8	2040	Montage	H1
Nanya Technology	NT16GA72D8PFX3K-JR	16GB	22	E2	Nanya	NT5AD1024M8F3-JR	8Gb	x8	2040	IDT	C1
Nanya Technology	NT32GA72D4NFX3P-JR	32GB	22	B2	Nanya	NT5AD2048M4F3-JR	8Gb	x4	2041	Montage	H1
Nanya Technology	NT32GA72D4NFX3K-JR	32GB	22	B2	Nanya	NT5AD2048M4F3-JR	8Gb	x4	2041	IDT	C1
Nanya Technology	NT16GA72D4PFX3P-JR	16GB	22	C2	Nanya	NT5AD2048M4F3-JR	8Gb	x4	2041	Montage	H1
Nanya Technology	NT16GA72D4PFX3K-JR	16GB	22	C2	Nanya	NT5AD2048M4F3-JR	8Gb	x4	2041	IDT	C1

Updated June 28, 2021



DDR4 RDIMM tested in the following conditions:  
3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

DIMM					DRAM					Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev
Samsung	M393A1K43DB2-CWE	8GB	22	D1	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	Rambus	B0
Samsung	M393A1K43DB2-CWE	8GB	22	D1	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	Montage	H1
Samsung	M393A1K43DB2-CWE	8GB	22	D1	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	IDT	C1
Samsung	M393A4K40DB3-CWE	32GB	22	B2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	Rambus	B0
Samsung	M393A4K40DB3-CWE	32GB	22	B2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	Montage	H1
Samsung	M393A4K40DB3-CWE	32GB	22	B2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	IDT	C1
Samsung	M393A2K40DB3-CWE	16GB	22	C2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	Rambus	B0
Samsung	M393A2K40DB3-CWE	16GB	22	C2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	Montage	H1
Samsung	M393A2K40DB3-CWE	16GB	22	C2	Samsung	K4A8G045WD-BCWE	8Gb	x4	1950	IDT	C1
Samsung	M393A2K43DB3-CWE	16GB	22	E2	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	Rambus	B0
Samsung	M393A2K43DB3-CWE	16GB	22	E2	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	Montage	H1
Samsung	M393A2K43DB3-CWE	16GB	22	E2	Samsung	K4A8G085WD-BCWE	8Gb	x8	1950	IDT	C1
Samsung	M393A4G40AB3-CWE	32GB	22	C3	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	Rambus	B0
Samsung	M393A4G40AB3-CWE	32GB	22	C3	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	Montage	H1
Samsung	M393A4G40AB3-CWE	32GB	22	C3	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	IDT	C1
Samsung	M393A8G40AB2-CWE	64GB	22	A2	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	Rambus	B0
Samsung	M393A8G40AB2-CWE	64GB	22	A2	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	IDT	C1
Samsung	M393A8G40AB2-CWE	64GB	22	A2	Samsung	K4AAG045WA-BCWE	16Gb	x4	1925	Montage	H1
Samsung	M393A4G43AB3-CWE	32GB	22	E3	Samsung	K4AAG085WA-BCWE	16Gb	x8	1928	Rambus	B0
Samsung	M393A4G43AB3-CWE	32GB	22	E3	Samsung	K4AAG085WA-BCWE	16Gb	x8	1928	Montage	H1
Samsung	M393A4G43AB3-CWE	32GB	22	E3	Samsung	K4AAG085WA-BCWE	16Gb	x8	1928	IDT	C1
Samsung	M393A2K40EB3-CWE	16GB	22	C2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2016	Rambus	B0
Samsung	M393A2K40EB3-CWE	16GB	22	C2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2016	Montage	H1
Samsung	M393A2K40EB3-CWE	16GB	22	C2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2016	IDT	C1
Samsung	M393A2K43EB3-CWE	16GB	22	E2	Samsung	K4A8G085WE-BCWE	8Gb	x8	2016	Rambus	B0
Samsung	M393A2K43EB3-CWE	16GB	22	E2	Samsung	K4A8G085WE-BCWE	8Gb	x8	2016	Montage	H1
Samsung	M393A2K43EB3-CWE	16GB	22	E2	Samsung	K4A8G085WE-BCWE	8Gb	x8	2016	IDT	C1
Samsung	M393A4K40EB3-CWE	32GB	22	B2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2037	Rambus	B0
Samsung	M393A4K40EB3-CWE	32GB	22	B2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2016	Montage	H1
Samsung	M393A4K40EB3-CWE	32GB	22	B2	Samsung	K4A8G045WE-BCWE	8Gb	x4	2016	IDT	C1
Samsung	M393A4G43BB4-CWE	32GB	22	E4	Samsung	K4AAG045WB-BCWE	16Gb	x8	2043	IDT	C1
Samsung	M393A4G43BB4-CWE	32GB	22	E4	Samsung	K4AAG045WB-BCWE	16Gb	x8	2043	Montage	H1
Samsung	M393A4G43BB4-CWE	32GB	22	E4	Samsung	K4AAG045WB-BCWE	16Gb	x8	2043	Rambus	B0
Samsung	M393A8G40BB4-CWE	64GB	22	B4	Samsung	K4AAG045WB-BCWE	16Gb	x4	2034	IDT	C1
Samsung	M393A8G40BB4-CWE	64GB	22	B4	Samsung	K4AAG045WB-BCWE	16Gb	x4	2034	Montage	H1
Samsung	M393A8G40BB4-CWE	64GB	22	B4	Samsung	K4AAG045WB-BCWE	16Gb	x4	2034	Rambus	B0

DDR4 RDIMM tested in the following conditions:  
 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

DIMM					DRAM					Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev
SK hynix	HMA84GR7CJR4N-XNT8	32GB	22	B2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1909	Rambus	B0
SK hynix	HMA84GR7CJR4N-XNT4	32GB	22	B2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1922	Montage	H1
SK hynix	HMA84GR7CJR4N-XNTG	32GB	22	B2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1922	IDT	C1
SK hynix	HMA82GR7CJR4N-XNT8	16GB	22	C2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1922	Rambus	B0
SK hynix	HMA82GR7CJR4N-XNT4	16GB	22	C2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1922	Montage	H1
SK hynix	HMA82GR7CJR4N-XNTG	16GB	22	C2	SK hynix	H5AN8G4NCJR-XNC	8Gb	x4	1922	IDT	C1
SK hynix	HMA82GR7CJR8N-XNT8	16GB	22	E2	SK hynix	H5AN8G8NCJR-XNC	8Gb	x8	1914	Rambus	B0
SK hynix	HMA82GR7CJR8N-XNT4	16GB	22	E2	SK hynix	H5AN8G8NCJR-XNC	8Gb	x8	1922	Montage	H1
SK hynix	HMA82GR7CJR8N-XNTG	16GB	22	E2	SK hynix	H5AN8G8NCJR-XNC	8Gb	x8	1922	IDT	C1
SK hynix	HMA84GR7DJR4N-XNT8	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	Rambus	B0
SK hynix	HMA84GR7DJR4N-XNT4	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	Montage	H1
SK hynix	HMA84GR7DJR4N-XNTG	32GB	22	B2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	IDT	C1
SK hynix	HMA82GR7DJR4N-XNT8	16GB	22	C2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	Rambus	B0
SK hynix	HMA82GR7DJR4N-XNT4	16GB	22	C2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	Montage	H1
SK hynix	HMA82GR7DJR4N-XNTG	16GB	22	C2	SK hynix	H5AN8G4NDJR-XNC	8Gb	x4	1924	IDT	C1
SK hynix	HMA82GR7DJR8N-XNT8	16GB	22	E2	SK hynix	H5AN8G8NDJR-XNC	8Gb	x8	1924	Rambus	B0
SK hynix	HMA82GR7DJR8N-XNT4	16GB	22	E2	SK hynix	H5AN8G8NDJR-XNC	8Gb	x8	1924	Montage	H1
SK hynix	HMA82GR7DJR8N-XNTG	16GB	22	E2	SK hynix	H5AN8G8NDJR-XNC	8Gb	x8	1924	IDT	C1
SK hynix	HMAA8GR7AJR4N-XNT8	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	Rambus	B0
SK hynix	HMAA8GR7AJR4N-XNTG	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	IDT	C1
SK hynix	HMAA8GR7AJR4N-XNT4	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	Montage	H1
SK hynix	HMAA4GR7AJR4N-XNT8	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	Rambus	B0
SK hynix	HMAA4GR7AJR4N-XNT4	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	Montage	H1
SK hynix	HMAA4GR7AJR4N-XNTG	32GB	22	C3	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	1927	IDT	C1
SK hynix	HMAA4GR7AJR8N-XNT8	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	1927	Rambus	B0
SK hynix	HMAA4GR7AJR8N-XNT4	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	1927	Montage	H1
SK hynix	HMAA4GR7AJR8N-XNTG	32GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	1927	IDT	C1



DDR4 RDIMM tested in the following conditions:  
 3200 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channels  
 2933 MT/s 1.2V 2DIMM per channel; 2 slots per channel; 8 channel

DIMM					DRAM					Register	
DIMM Supplier	DIMM Part Number	Size	CL	Raw Card	DRAM Supplier	DRAM Part Number	Die Density	Width	Date Code	Register Vendor	Register Rev
SK hynix	HMAA8GR7CJR4N-XNT8	64GB	22	B2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2018	Rambus	B0
SK hynix	HMAA8GR7CJR4N-XNT4	64GB	22	B2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2018	Montage	H1
SK hynix	HMAA8GR7CJR4N-XNTG	64GB	22	B2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2018	IDT	C1
SK hynix	HMAA4GR7CJR4N-XNT8	32GB	22	C2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2017	Rambus	B0
SK hynix	HMAA4GR7CJR4N-XNT4	32GB	22	C2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2017	Montage	H1
SK hynix	HMAA4GR7CJR4N-XNTG	32GB	22	C2	SK hynix	H5ANAG4NCJR-XNC	16Gb	x4	2017	IDT	C1
SK hynix	HMAA4GR7CJR8N-XNT8	32GB	22	E2	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2017	Rambus	B0
SK hynix	HMAA4GR7CJR8N-XNT4	32GB	22	E2	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2017	Montage	H1
SK hynix	HMAA4GR7CJR8N-XNTG	32GB	22	E2	SK hynix	H5ANAG8NCJR-XNC	16Gb	x8	2017	IDT	C1
SK hynix	HMABAGR7A2R4N-XST4	128GB	26	B4	SK hynix	H5ANBG4TA2R-XSC	16Gb 3DS	x4	1930	Montage	H1
SK hynix	HMABAGR7A2R4N-XSTG	128GB	26	B4	SK hynix	H5ANBG4TA2R-XSC	16Gb 3DS	x4	1930	IDT	C1
SK hynix	HMAT14JXSRB120N	256GB	26	B3	SK hynix	H5AG64JXSDX042	16Gb 3DS	x4	2037	Montage	H1
SK hynix	HMAT14JXSRB122N	256GB	26	B3	SK hynix	H5AG64JXSDX042	16Gb 3DS	x4	2037	IDT	C1
UnilC	SCC32GP13H2F1C-32AA	16GB	22	E4	SK hynix	H5ANAG8NAJR-XNC	16Gb	x8	2028	Rambus	B0
UnilC	SCC64GP12H2F1C-32AA	64GB	22	B4	SK hynix	H5ANAG4NAJR-XNC	16Gb	x4	2009	Montage	H1

# Approved Test Labs

The following test labs have the capability of performing ATE and system-level validation testing:

## **Advanced Validation Labs**

Attn: Rhonda Duda  
Advanced Validation Labs,  
17665B Newhope Street  
Fountain Valley, CA 92708  
USA Phone: 714-438-2787  
<mailto:rduda@validationlabs.com>